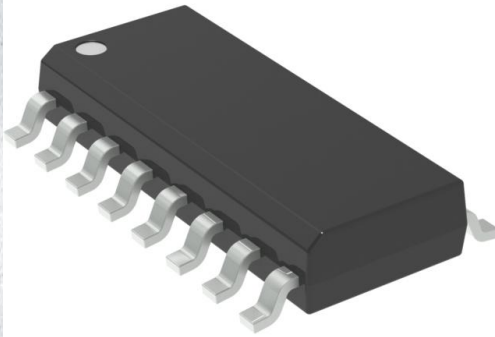


# MC74HCT4094ADTG Datasheet

[www.digi-electronics.com](http://www.digi-electronics.com)



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	MC74HCT4094ADTG-DG
Manufacturer	<a href="#">onsemi</a>
Manufacturer Product Number	MC74HCT4094ADTG
Description	IC BUS REG TRE-ST 8STG 16TSSOP
Detailed Description	Shift Shift Register 1 Element 8 Bit 16-SOIC



Tel: +00 852-30501935

RFQ Email: [Info@DiGi-Electronics.com](mailto:Info@DiGi-Electronics.com)

DiGi is a global authorized distributor of electronic components.

## Purchase and inquiry

Manufacturer Product Number:

MC74HCT4094ADTG

Series:

74HCT

Logic Type:

Shift Register

Number of Elements:

1

Function:

Serial to Parallel

Operating Temperature:

-55°C ~ 125°C

Package / Case:

16-SOIC (0.154", 3.90mm Width)

Base Product Number:

74HCT4094

Manufacturer:

onsemi

Product Status:

Obsolete

Output Type:

Tri-State

Number of Bits per Element:

8

Voltage - Supply:

4.5V ~ 5.5V

Mounting Type:

Surface Mount

Supplier Device Package:

16-SOIC

## Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8542.39.0001

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99



# MC74HCT4094A

## 8-Bit Shift and Store Register with LSTTL Compatible Inputs

### High-Performance Silicon-Gate CMOS

The MC74HCT4094A is a high speed CMOS 8-bit serial shift and storage register. This device consists of an 8-bit shift register and latch with 3-state output buffers. Data is shifted on positive clock (CP) transitions. The data in the shift register is transferred to the storage register when the Strobe (STR) input is high. The output buffers are enabled when the Output Enable (OE) input is set high. Two serial outputs (QS<sub>1</sub>, QS<sub>2</sub>) are available for cascading multiple devices.

The MC74HCT4094A can be used to interface TTL or CMOS outputs to high speed CMOS inputs.

#### Features

- Wide Operating Voltage Range: 4.5 to 5.5 V
- Low Power Dissipation: I<sub>CC</sub> = < 10 μA
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- These are Pb-Free Devices

#### Typical Applications

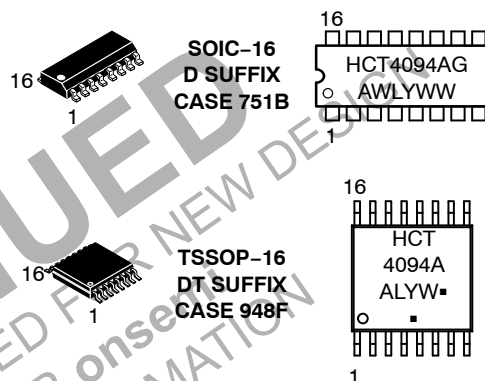
- Serial-to-Parallel Conversion
- Remote Control Storage Register



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<http://onsemi.com>

#### MARKING DIAGRAMS



A = Assembly Location  
WL, L = Wafer Lot  
YY, Y = Year  
WW, W = Work Week  
G, ■ = Pb-Free Package

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

### MC74HCT4094A

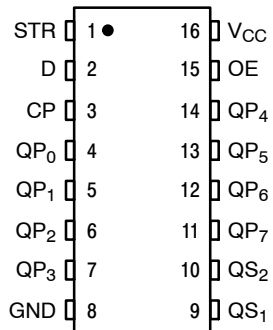


Figure 1. Pin Assignment

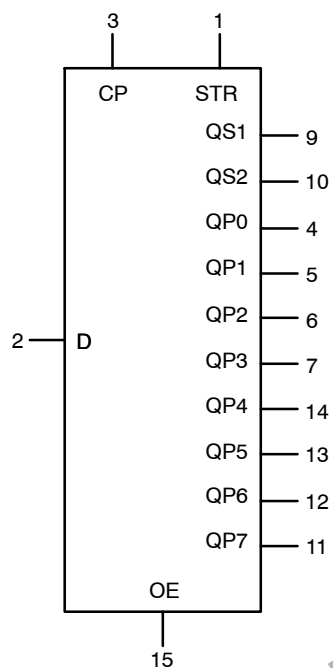


Figure 2. Logic Symbol

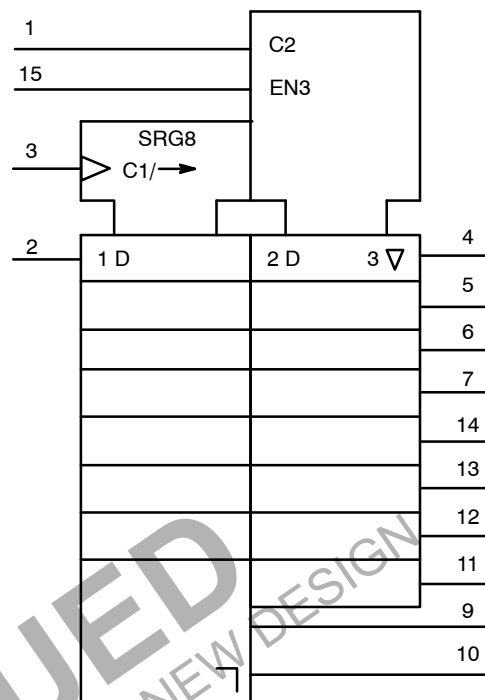


Figure 3. IEC Logic Symbol

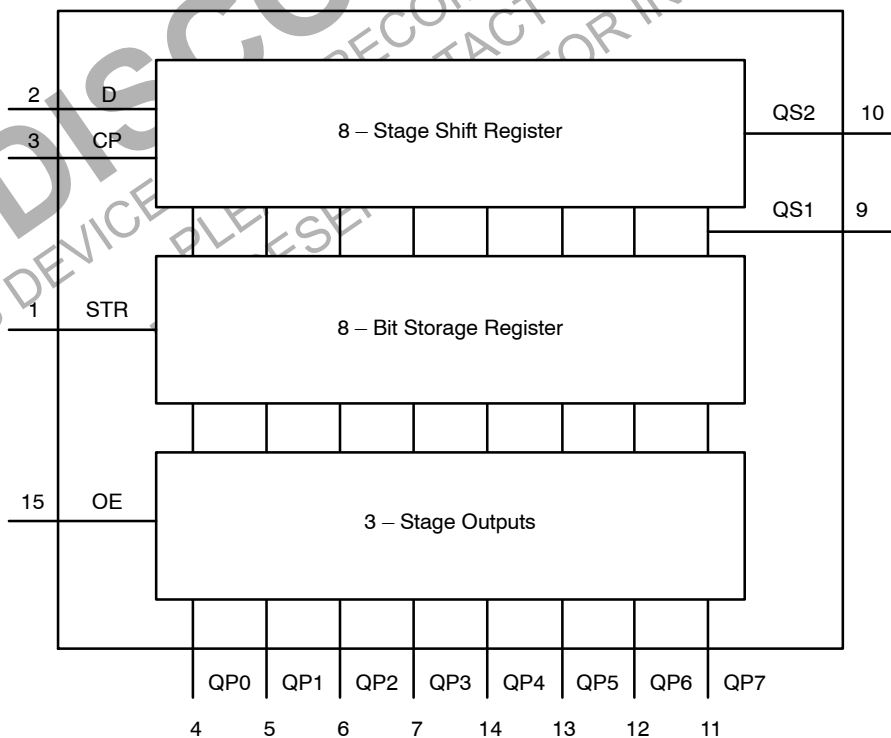


Figure 4. Functional Diagram



**MC74HCT4094A****MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
$V_{CC}$	DC Supply Voltage (Referenced to GND)	- 0.5 to + 7.0	V
$V_{in}$	DC Input Voltage (Referenced to GND)	- 0.5 to $V_{CC} + 0.5$	V
$V_{out}$	DC Output Voltage (Referenced to GND)	- 0.5 to $V_{CC} + 0.5$	V
$I_{in}$	DC Input Current, per Pin	$\pm 20$	mA
$I_{out}$	DC Output Current, per Pin	$\pm 35$	mA
$I_{CC}$	DC Supply Current, $V_{CC}$ and GND Pins	$\pm 75$	mA
$P_D$	Power Dissipation in Still Air, SOIC Package† TSSOP Package†	500 450	mW
$T_{stg}$	Storage Temperature	- 65 to + 150	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $GND \leq (V_{in} \text{ or } V_{out}) \leq V_{CC}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

†Derating – SOIC Package: - 7 mW/°C from 65° to 125°C  
TSSOP Package: - 6.1 mW/°C from 65° to 125°C

**RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit
$V_{CC}$	DC Supply Voltage (Referenced to GND)	4.5	5.5	V
$V_{in}, V_{out}$	DC Input Voltage, Output Voltage (Referenced to GND)	0	$V_{CC}$	V
$T_A$	Operating Temperature, All Package Types	-55	+125	°C
$t_r, t_f$	Input Rise and Fall Time (Figure 1)	0	500	ns

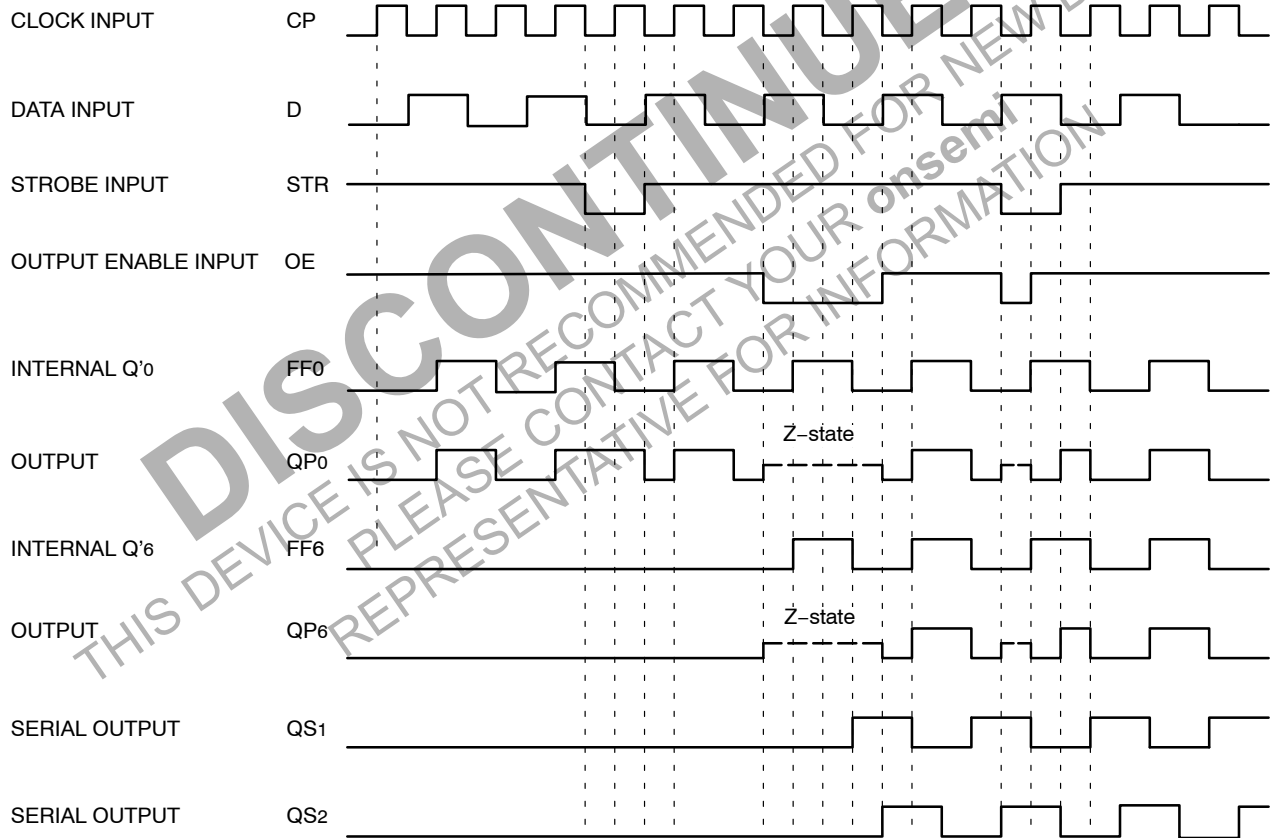
**DISCONTINUED**  
THIS DEVICE IS NOT RECOMMENDED FOR NEW DESIGN  
PLEASE CONTACT YOUR onsemi  
REPRESENTATIVE FOR INFORMATION

**MC74HCT4094A****FUNCTIONAL TABLE**

INPUTS				PARALLEL OUTPUTS		SERIAL OUTPUTS	
CP	OE	STR	D	QP0	QPn	QS1	QS2
↑	L	X	X	Z	Z	Q'6	NC
↓	L	X	X	Z	Z	NC	QP7
↑	H	L	X	NC	NC	Q'6	NC
↑	H	H	L	L	QPn-1	Q'6	NC
↑	H	H	H	H	QPn-1	Q'6	NC
↓	H	H	H	NC	NC	NC	QP7

**Notes**

- H = HIGH voltage level  
L = LOW voltage level  
X = don't care  
Z = high impedance OFF-state  
NC = no change  
↑ = LOW-to-HIGH CP transition  
↓ = HIGH-to-LOW CP transition  
Q'6 = the information in the seventh register stage is transferred to the 8th register stage and QSn output at the positive clock edge

**Figure 6. Timing Diagram**

**MC74HCT4094A****DC CHARACTERISTICS**

Symbol	Parameter	Test Conditions	V <sub>CC</sub> (V)	Guaranteed Limits			Unit
				−55°C to 25°C	≤ 85°C	≤ 125°C	
V <sub>IH</sub>	Minimum High-Level Input Voltage	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> − 0.1 V  I <sub>OUT</sub>   ≤ 20 μA	4.5	2.0	2.0	2.0	V
			5.5	2.0	2.0	2.0	
V <sub>IL</sub>	Maximum Low-Level Input Voltage	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> − 0.1 V  I <sub>OUT</sub>   ≤ 20 μA	4.5	0.8	0.8	0.8	V
			5.5	0.8	0.8	0.8	
V <sub>OH</sub>	Minimum High-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub>  I <sub>OUT</sub>   ≤ 20 μA	4.5	4.4	4.4	4.4	V
			5.5	5.4	5.4	5.4	
		V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> ,  I <sub>OUT</sub>   = 6 mA	4.5	4.25	4.2	4.1	
V <sub>OL</sub>	Maximum Low-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> ,  I <sub>OUT</sub>   ≤ 20 μA	4.5	0.1	0.1	0.1	V
			5.5	0.1	0.1	0.1	
		V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> ,  I <sub>OUT</sub>   = 6 mA	4.5	0.25	0.3	0.4	
I <sub>IN</sub>	Maximum Input Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5	±0.1	±1	±1	μA
I <sub>OZ</sub>	Maximum Tri-State Output Leakage Current	V <sub>IN</sub> = V <sub>CC</sub> or GND V <sub>OUT</sub> = V <sub>CC</sub> or GND	5.5	±0.5	±5	±10	μA
I <sub>CC</sub>	Maximum Quiescent Supply Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5	4.0	40	80	μA
ΔI <sub>CC</sub>	Additional Quiescent Supply Current	V <sub>in</sub> = 2.4V, Any One Input V <sub>in</sub> = V <sub>CC</sub> or GND, Other Inputs I <sub>out</sub> = 0μA	5.5	≥ −55°C	25 to 125°C		mA
				2.9	2.4		

**DISCONTINUED**  
THIS DEVICE IS NOT RECOMMENDED FOR NEW DESIGN  
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## MC74HCT4094A

AC CHARACTERISTICS ( $t_f = t_r = 6 \text{ ns}$ ,  $C_L = 50 \text{ pF}$ )

Symbol	Parameter	Test Conditions	V <sub>CC</sub> (V)	Guaranteed Limits			Unit
				-55°C to 25°C	≤ 85°C	≤ 125°C	
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay CP to QS <sub>1</sub>	Figure 7	4.5	30	38	45	ns
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay CP to QS <sub>2</sub>	Figure 7	4.5	27	34	41	ns
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay CP to QP <sub>n</sub>	Figure 7	4.5	39	49	59	ns
$t_{PHL}$ , $t_{PLH}$	Maximum Propagation Delay STR to QP <sub>n</sub>	Figure 8	4.5	36	45	54	ns
$t_{PZH}$ , $t_{PZL}$	Maximum 3-State Output Enable Time OE to QP <sub>n</sub>	Figure 9	4.5	35	44	53	ns
$t_{PHZ}$ , $t_{PLZ}$	Maximum 3-State Output Enable Time OE to QP <sub>n</sub>	Figure 9	4.5	25	31	38	ns
$t_{THL}$ , $t_{TLH}$	Maximum Output Transition Time	Figure 7	4.5	18	22	25	ns
$t_W$	Minimum Clock Pulse Width High or Low	Figure 7	4.5	16	20	24	ns
$t_W$	Minimum Strobe Pulse Width High	Figure 8	4.5	16	20	24	ns
$t_{SU}$	Minimum Set-up Time D to CP	Figure 10	4.5	10	13	15	ns
$t_{SU}$	Minimum Set-up Time CP to STR	Figure 8	4.5	20	25	30	ns
$t_h$	Minimum Hold Time D to CP	Figure 10	4.5	3	3	3	ns
$t_h$	Minimum Hold Time CP to STR	Figure 8	4.5	0	0	0	ns
$f_{MAX}$	Minimum Clock Pulse Frequency	Figure 7	4.5	30	24	20	MHz
$C_{in}$	Maximum Input Capacitance		-	10	10	10	pF
$C_{out}$	Maximum Output Capacitance		-	15	15	15	pF
$C_{PD}$	Power Dissipation Capacitance (Note 2)		-	140	140	140	pF

2.  $C_{PD}$  is defined as the value of the IC's equivalent capacitance from which the operating current can be calculated from:  
 $I_{CC(operating)} \approx C_{PD} \times V_{CC} \times f_{IN} \times N_{SW}$  where  $N_{SW}$  = total number of outputs switching and  $f_{IN}$  = switching frequency.

# MC74HCT4094A

## AC WAVEFORMS

( $V_M = 1.3\text{ V}$ )

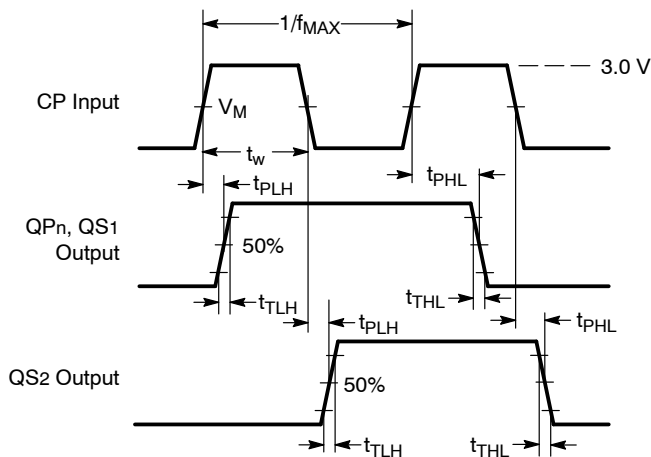


Figure 7. Waveforms showing the clock (CP) to output (QPn, QS1, QS2) propagation delays, the clock pulse width and the maximum clock frequency.

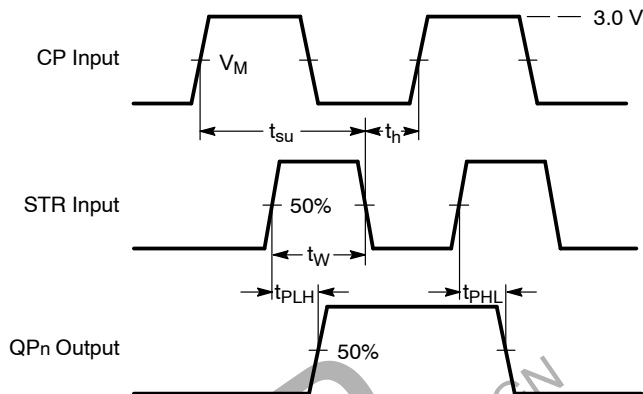


Figure 8. Waveforms showing the strobe (STR) to output (QPn) propagation delays, the strobe pulse width, the clock set-up and hold times for the strobe input.

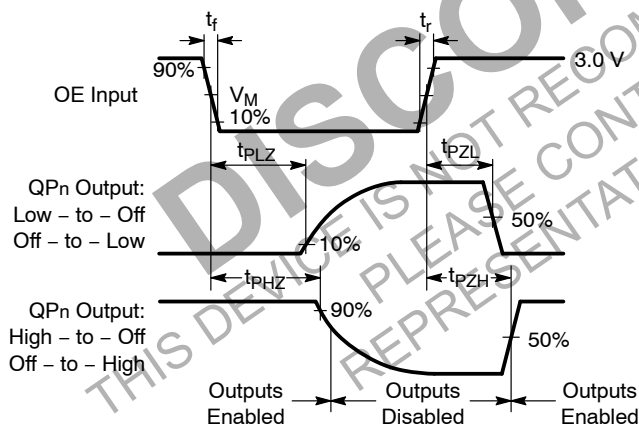


Figure 9. Waveforms showing the 3-state enable and disable times for input OE.

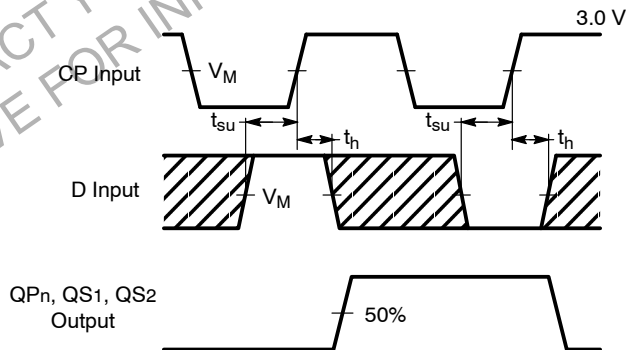
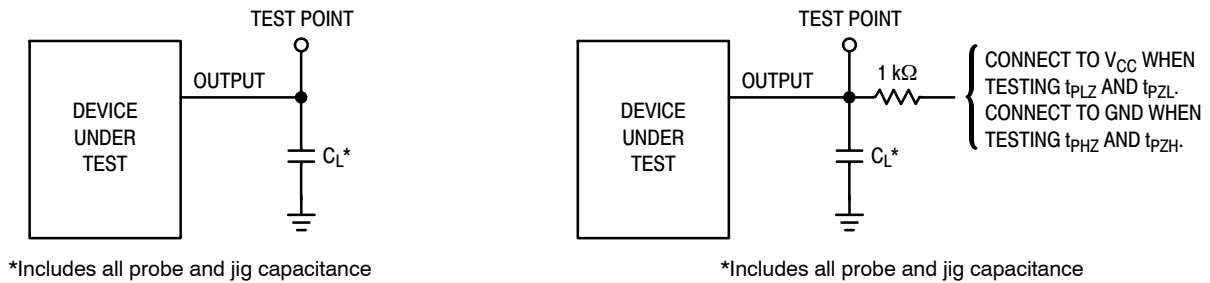


Figure 10. Waveforms showing the data set-up and hold times for the data input.

The shaded areas indicate when the input is permitted to change for predictable output performance.

**MC74HCT4094A****TEST CIRCUITS****Figure 11. AC Characteristics Load Circuits****ORDERING INFORMATION**

Device	Package	Shipping†
MC74HCT4094ADG	SOIC-16 (Pb-Free)	48 Units/ Rail
MC74HCT4094ADR2G	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC74HCT4094ADT	TSSOP-16*	96 Units / Rail
MC74HCT4094ADTR2G	TSSOP-16*	2500 Tape & Reel

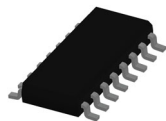
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*This package is inherently Pb-Free.

**DISCONTINUED**  
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**MECHANICAL CASE OUTLINE  
PACKAGE DIMENSIONS**

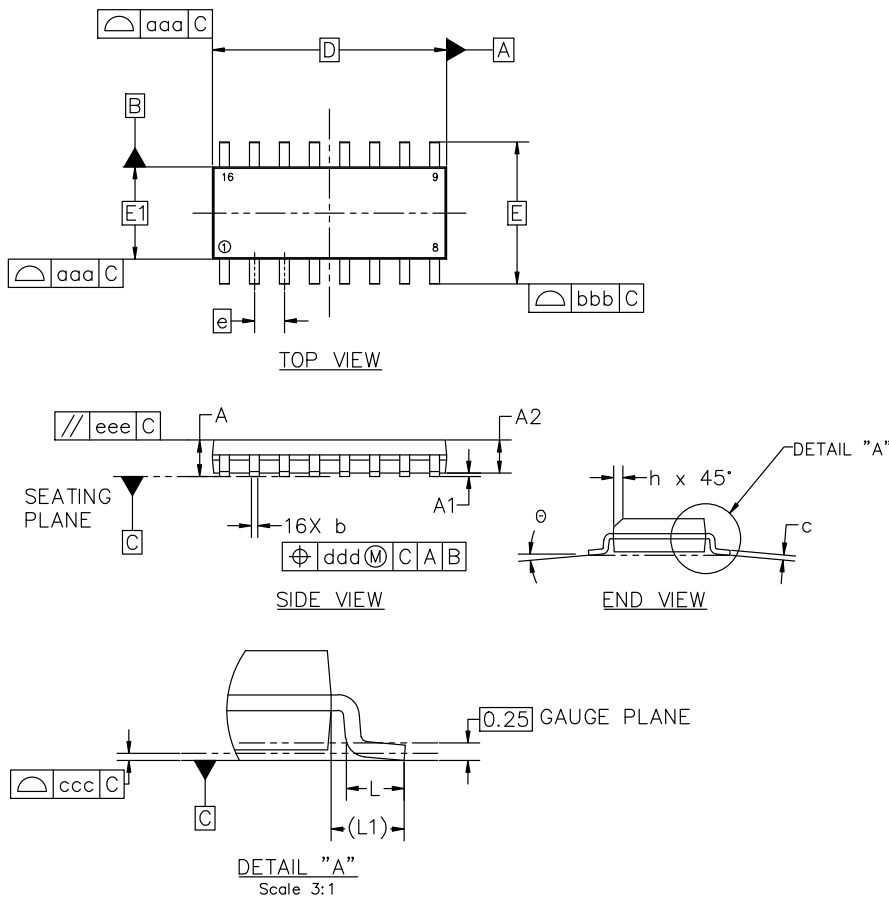


**SOIC-16 9.90x3.90x1.37 1.27P  
CASE 751B  
ISSUE M**

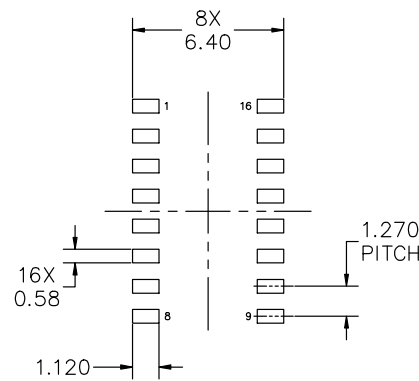
DATE 18 OCT 2024

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. DIMENSION IN MILLIMETERS. ANGLE IN DEGREES.
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15mm PER SIDE.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127mm TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.



MILLIMETERS			
DIM	MIN	NOM	MAX
A	1.35	1.55	1.75
A1	0.10	0.18	0.25
A2	1.25	1.37	1.50
b	0.35	0.42	0.49
c	0.19	0.22	0.25
D	9.90 BSC		
E	6.00 BSC		
E1	3.90 BSC		
e	1.27 BSC		
h	0.25	---	0.50
L	0.40	0.83	1.25
L1	1.05 REF		
θ	0°	---	7°
TOLERANCE OF FORM AND POSITION			
aaa	0.10		
bbb	0.20		
ccc	0.10		
ddd	0.25		
eee	0.10		



RECOMMENDED MOUNTING FOOTPRINT

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE onsemi SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D

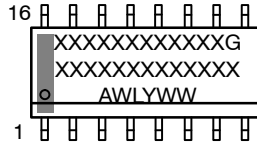
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<b>DESCRIPTION:</b>	<b>SOIC-16 9.90X3.90X1.37 1.27P</b>	<b>PAGE 1 OF 2</b>

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**SOIC-16 9.90x3.90x1.37 1.27P**  
**CASE 751B**  
**ISSUE M**

DATE 18 OCT 2024

**GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code  
 A = Assembly Location  
 WL = Wafer Lot  
 Y = Year  
 WW = Work Week  
 G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

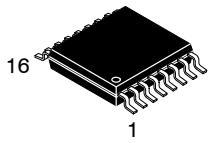
<p><b>STYLE 1:</b></p> <p>PIN 1. COLLECTOR                  2. BASE                  3. EMITTER                  4. NO CONNECTION                  5. EMITTER                  6. BASE                  7. COLLECTOR                  8. COLLECTOR                  9. BASE                  10. EMITTER                  11. NO CONNECTION                  12. EMITTER                  13. BASE                  14. COLLECTOR                  15. EMITTER                  16. COLLECTOR</p>	<p><b>STYLE 2:</b></p> <p>PIN 1. CATHODE                  2. ANODE                  3. NO CONNECTION                  4. CATHODE                  5. CATHODE                  6. NO CONNECTION                  7. ANODE                  8. CATHODE                  9. CATHODE                  10. ANODE                  11. NO CONNECTION                  12. CATHODE                  13. CATHODE                  14. NO CONNECTION                  15. ANODE                  16. CATHODE</p>	<p><b>STYLE 3:</b></p> <p>PIN 1. COLLECTOR, DYE #1                  2. BASE, #1                  3. EMITTER, #1                  4. COLLECTOR, #1                  5. COLLECTOR, #2                  6. BASE, #2                  7. EMITTER, #2                  8. COLLECTOR, #2                  9. COLLECTOR, #3                  10. BASE, #3                  11. EMITTER, #3                  12. COLLECTOR, #3                  13. COLLECTOR, #4                  14. BASE, #4                  15. EMITTER, #4                  16. COLLECTOR, #4</p>	<p><b>STYLE 4:</b></p> <p>PIN 1. COLLECTOR, DYE #1                  2. COLLECTOR, #1                  3. COLLECTOR, #2                  4. COLLECTOR, #2                  5. COLLECTOR, #3                  6. COLLECTOR, #3                  7. COLLECTOR, #4                  8. COLLECTOR, #4                  9. BASE, #4                  10. EMITTER, #4                  11. BASE, #3                  12. EMITTER, #3                  13. BASE, #2                  14. EMITTER, #2                  15. BASE, #1                  16. EMITTER, #1</p>
<p><b>STYLE 5:</b></p> <p>PIN 1. DRAIN, DYE #1                  2. DRAIN, #1                  3. DRAIN, #2                  4. DRAIN, #2                  5. DRAIN, #3                  6. DRAIN, #3                  7. DRAIN, #4                  8. DRAIN, #4                  9. GATE, #4                  10. SOURCE, #4                  11. GATE, #3                  12. SOURCE, #3                  13. GATE, #2                  14. SOURCE, #2                  15. GATE, #1                  16. SOURCE, #1</p>	<p><b>STYLE 6:</b></p> <p>PIN 1. CATHODE                  2. CATHODE                  3. CATHODE                  4. CATHODE                  5. CATHODE                  6. CATHODE                  7. CATHODE                  8. CATHODE                  9. ANODE                  10. ANODE                  11. ANODE                  12. ANODE                  13. ANODE                  14. ANODE                  15. ANODE                  16. ANODE</p>	<p><b>STYLE 7:</b></p> <p>PIN 1. SOURCE N-CH                  2. COMMON DRAIN (OUTPUT)                  3. COMMON DRAIN (OUTPUT)                  4. GATE P-CH                  5. COMMON DRAIN (OUTPUT)                  6. COMMON DRAIN (OUTPUT)                  7. COMMON DRAIN (OUTPUT)                  8. SOURCE P-CH                  9. SOURCE P-CH                  10. COMMON DRAIN (OUTPUT)                  11. COMMON DRAIN (OUTPUT)                  12. COMMON DRAIN (OUTPUT)                  13. GATE N-CH                  14. COMMON DRAIN (OUTPUT)                  15. COMMON DRAIN (OUTPUT)                  16. SOURCE N-CH</p>	

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<b>DESCRIPTION:</b>	<b>SOIC-16 9.90X3.90X1.37 1.27P</b>	<b>PAGE 2 OF 2</b>

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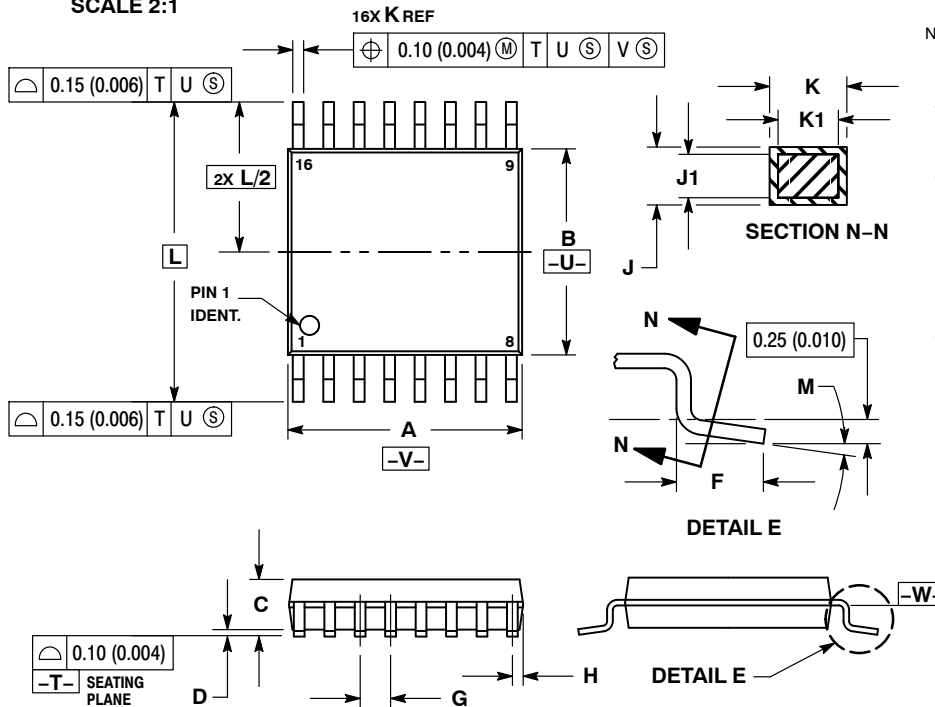


**MECHANICAL CASE OUTLINE  
PACKAGE DIMENSIONS**



**TSSOP-16 WB  
CASE 948F  
ISSUE B**

DATE 19 OCT 2006

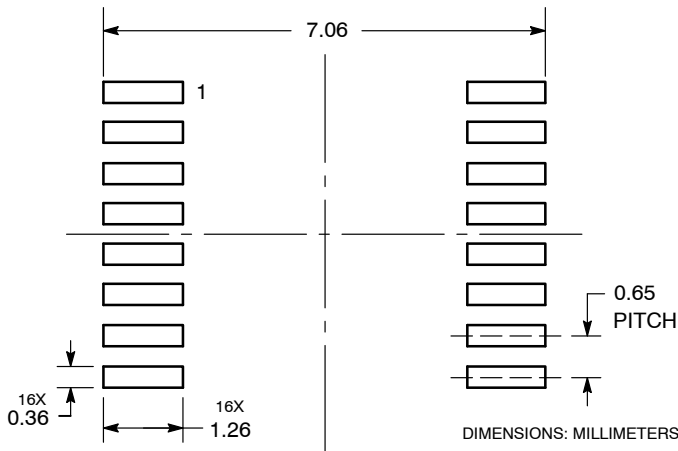


**NOTES:**

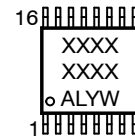
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

**RECOMMENDED  
SOLDERING FOOTPRINT\***



**GENERIC  
MARKING DIAGRAM\***



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- G or ■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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